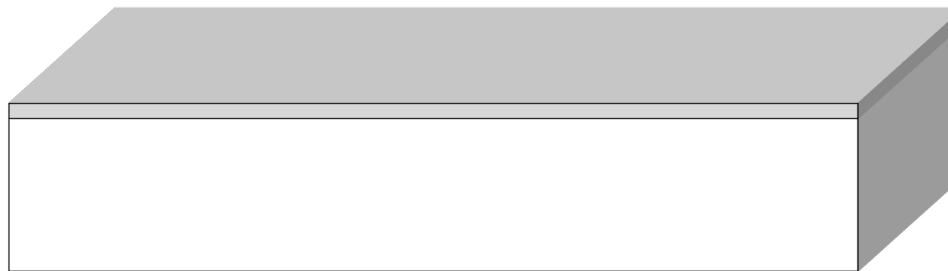







Step 1: Substrate Stack

- **Width:** 5000 nm
- 5000 nm
- **Layer 1:** Silicon
- **Thickness:** 1000 nm
- **Layer 2:** Gunk
- **Thickness:** 100 nm

Comments: 111 crystal axis



	Silicon
	Gunk
	MMA EL13
	PMMA A6
	Aluminium

Step 2: 3 Solvent Clean

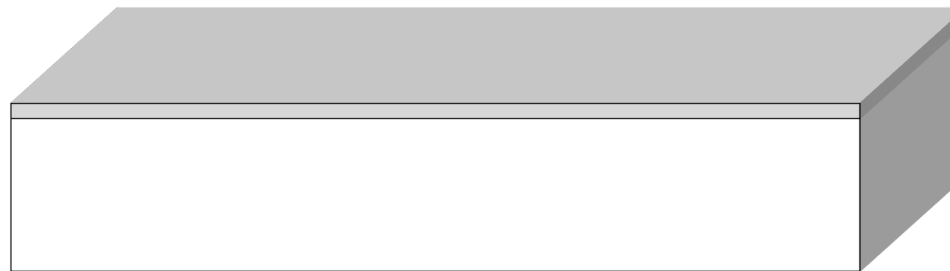
Beakers + Sonicator





- **Chemical:** Acetone
- **Time:** 5 mins
- **Temp:** 20 °C
- **Ultra Sonic:** true

Comments: Sonicate in Acetone for 6 minutes

Sonicate in Methanol for 3 minutes

Sonicate in IPA for 3 minutes



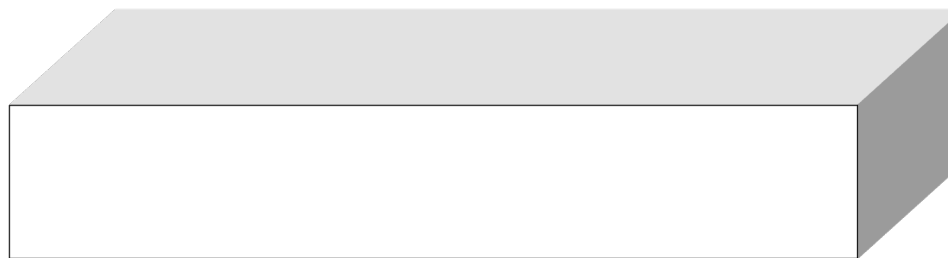
-  Silicon
-  Gunk
-  MMA EL13
-  PMMA A6
-  Aluminium






Step 3: DI Water Rinse

Beakers

- **Chemical:** DI Water
- **Time:** 30 secs
- **Temp:** 25 °C
- **Ultra Sonic:** false

Comments: Dry with N2 gun



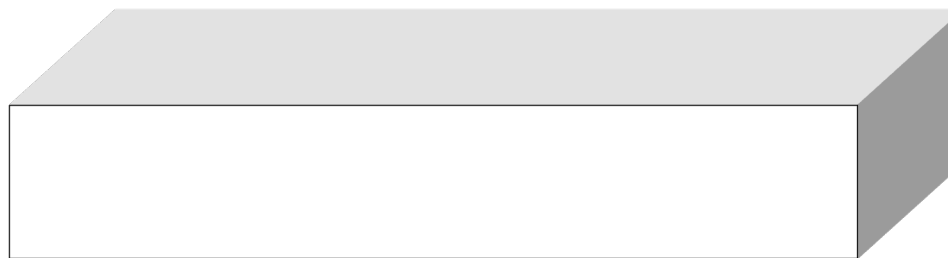
-  Silicon
-  Gunk
-  MMA EL13
-  PMMA A6
-  Aluminium





Step 4: Dehydration Bake

Bake Plate

- **Temp:** 110 °C
- **Time:** 20 secs

Comments: 110 to 180 degree C allowed



-  Silicon
-  Gunk
-  MMA EL13
-  PMMA A6
-  Aluminium

Step 5: Spin Resist

Spinner

- **Material:** MMA EL13
- **Thickness:** 620 nm
- **Spin Speed:** 3000 rpm
- **Spin Time:** 60 secs

Comments:



Step 6: Softbake

Bake Plate

- **Temp:** 180 °C
- **Time:** 300 secs

Comments:

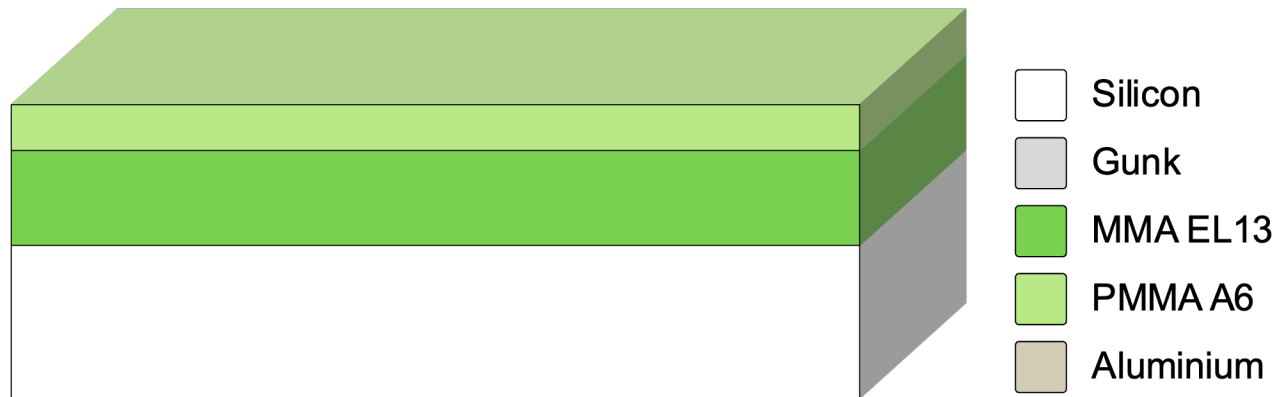


Step 7: Spin Resist

Spinner

- **Material:** PMMA A6
- **Thickness:** 300 nm
- **Spin Speed:** 4000 rpm
- **Spin Time:** 60 secs

Comments:

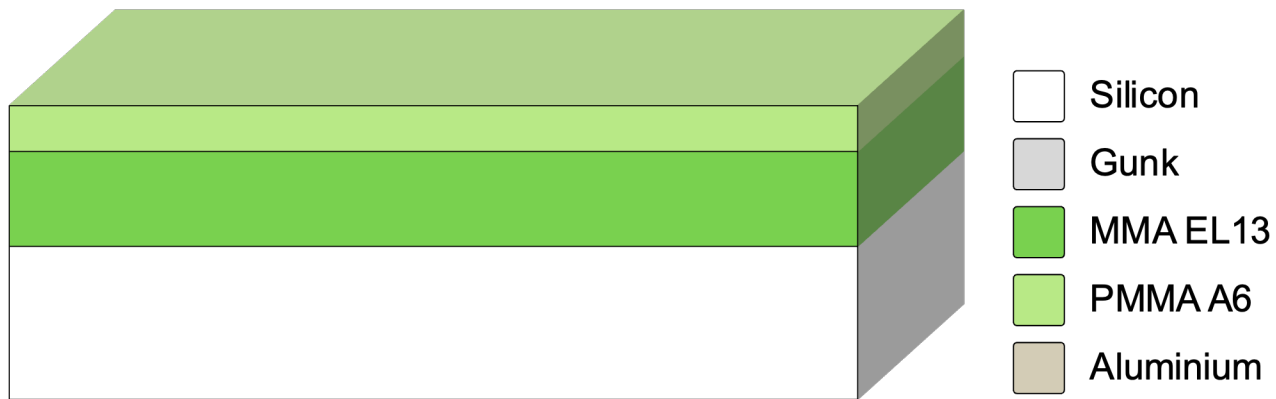


Step 8: Softbake

Bake Plate

- **Temp:** 180 °C
- **Time:** 300 secs

Comments:

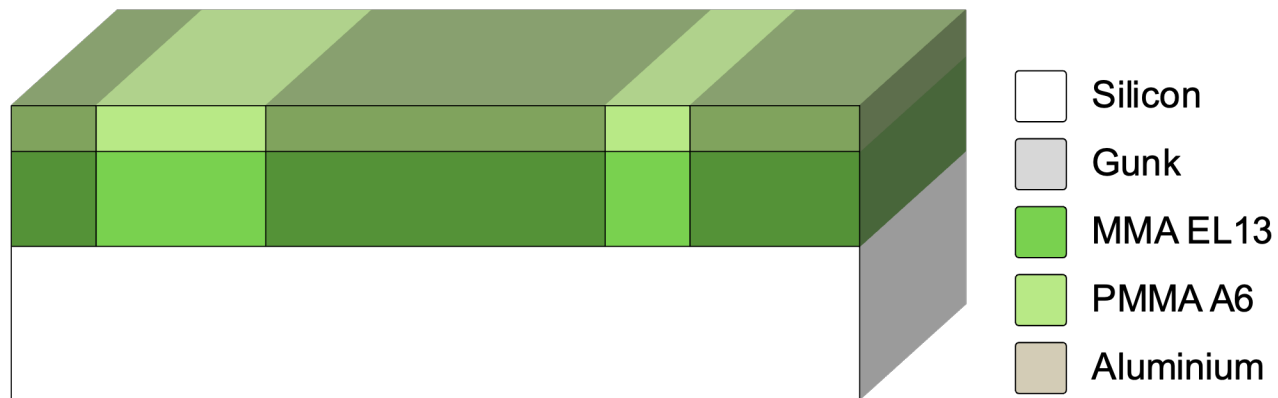


Step 9: Electron-Beam Lithography

Raith EBPG 5150

- **Voltage:** 100 kV
- **Current:** 100 nA
- **Dose:** 290 $\mu\text{C}/\text{cm}^2$
- **Dwell Time:** <none> ns

Comments:

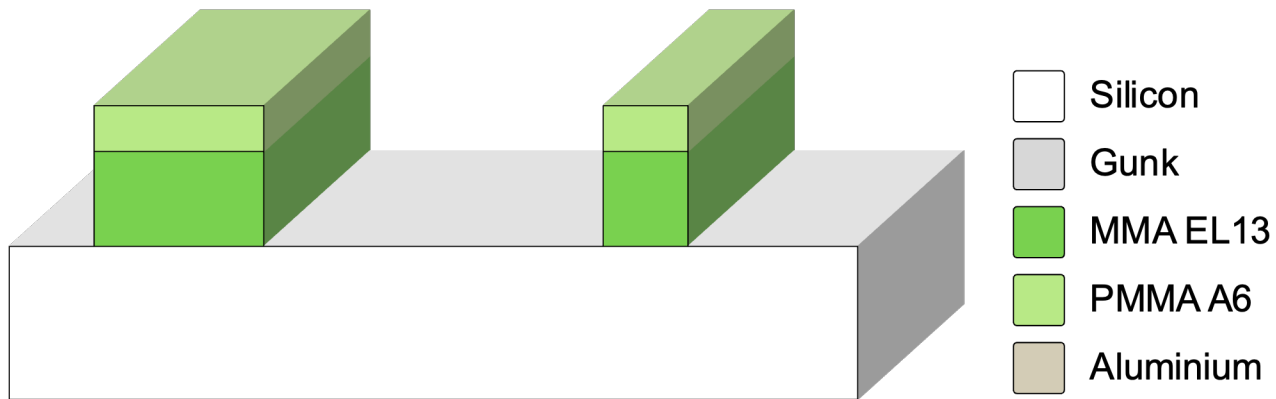


Step 10: Develop

Beaker

- **Developer:** MIBK:IPA
- **Time:** 180 secs
- **Temp:** 20 °C

Comments: MIBK:IPA = 1:1

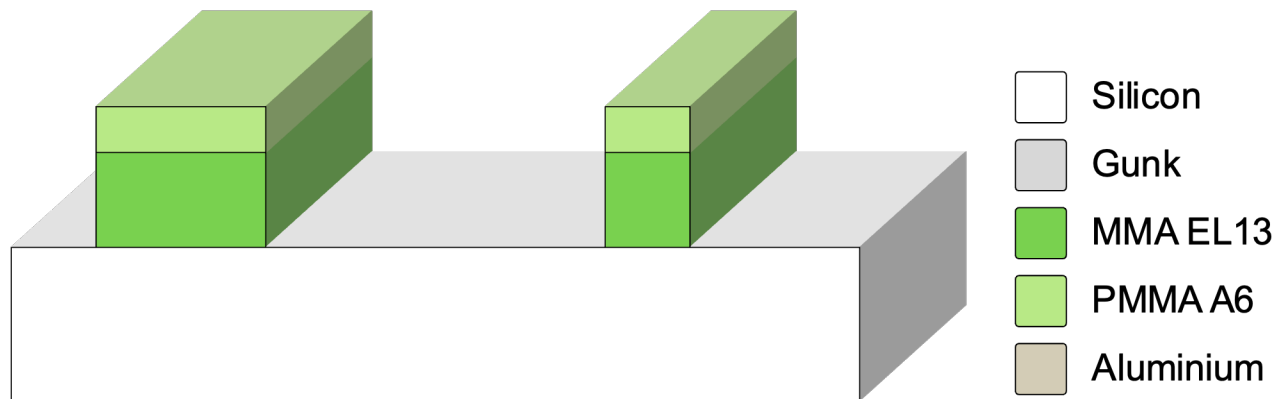


Step 11: Pre-Ash

YES O2 Plasma

- **Material:** Gunk
- **Depth:** 0 nm
- **Gasses:** Oxygen
- **Etch Rate:** <none> nm/s
- **Time:** 30 secs
- **RF Power:** 60 Watts
- **Pressure:** 0.3 Torr
-

Comments:

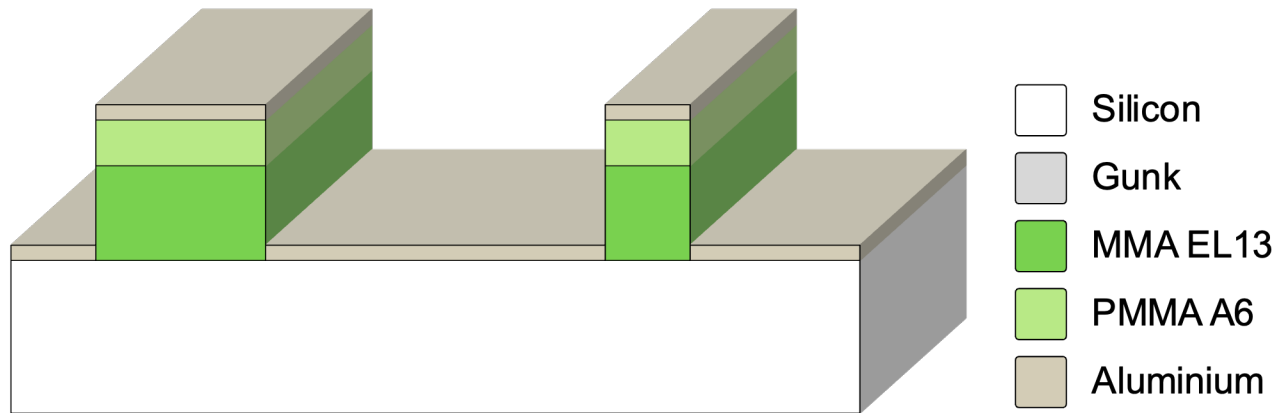


Step 12: E-beam Evaporation

Angstrom

- **Material:** Aluminium
- **Thickness:** 1000 Å
- **Deposition Rate:** 4 Å/s
- **Beam Current:** <none> Amps
- **Beam Voltage:** <none> kV
- **Pressure:** <none> Torr
- **Deposition Angle:** 0°

Comments:

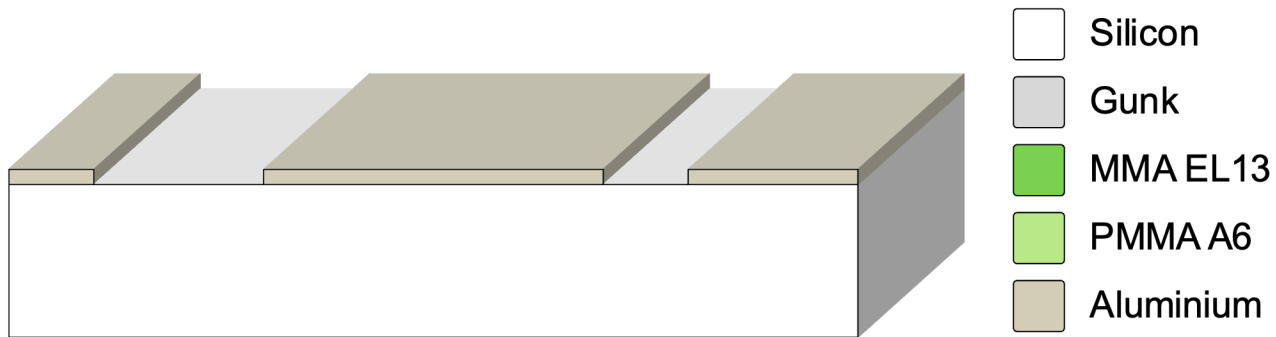


Step 13: Lift-Off

Beaker + Sonicator

- **Solvent:** Acetone
- **Time:** 3 hours
- **Temp:** 45 °C

Comments:



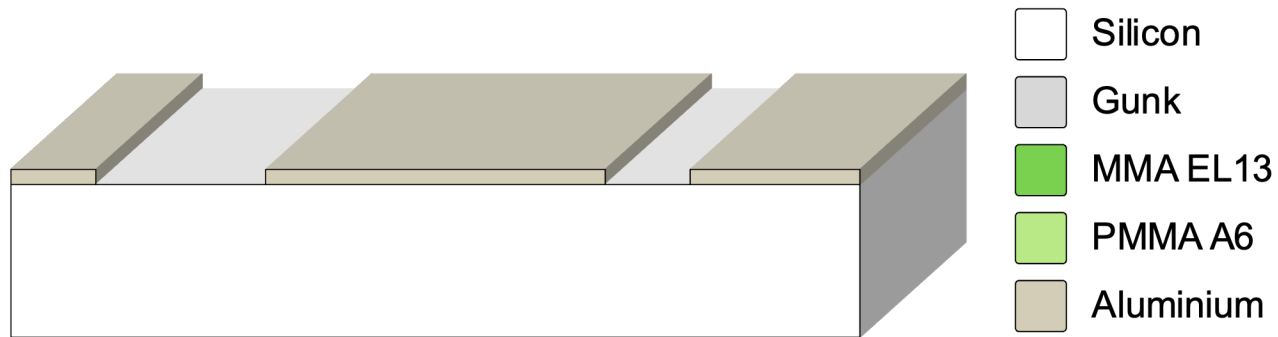
Step 14: 3 Solvent Clean

Beaker

- **Chemical:** Acetone
- **Time:** 30 secs
- **Temp:** 25 °C
- **Ultra Sonic:** true

Comments: Sonicate the chip in the acetone liftoff beaker for 30 seconds (more time if the liftoff has not been completed.)

With the acetone wash bottle in the other hand, take the chip out of the acetone slowly as maintaining a CUSTOM CLEAN



Step 15: DI Water Rinse

Beaker

- **Chemical:** DI Water
- **Time:** 30 secs
- **Temp:** 25 °C
- **Ultra Sonic:** false

Comments: Dry with N2 gun

